PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Takanori HIRAMOTO	04/26/2012
Toshio HINO	04/26/2012
Tsuyoshi SAKATA	04/26/2012
Yutaka MIZUNO	04/26/2012
Katsuya OGATA	04/26/2012

RECEIVING PARTY DATA

Name:	FUJITSU SEMICONDUCTOR LIMITED
Street Address:	2-10-23 Shin-Yokohama, Kohoku-ku
City:	Yokohama-shi, Kanagawa
State/Country:	JAPAN
Postal Code:	222-0033

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13494145

OP $40.00 13494145

CORRESPONDENCE DATA

Fax Number: (202)822-1111
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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.

Correspondent Name: Westerman, Hattori, Daniels & Adrian, LL
Address Line 1: 1250 Connecticut Ave., NW
Address Line 2: Suite 700
Address Line 4: Washington, DISTRICT OF COLUMBIA 20036

ATTORNEY DOCKET NUMBER:	111599
NAME OF SUBMITTER:	Crystal Boyer

Total Attachments: 5
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source=111599_Assignment_06-11-2012#page5.tif

U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar ($1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter, "ASSIGNOR") by
(Insert Name(s) & Address(es) of ASSIGNEE(S))

FUJITSU SEMICONDUCTOR LIMITED
2-10-23 Shin-Yokohama, Kohoku-ku, Yokohama-shi, Kanagawa 222-0033 Japan

(hereinafter, "ASSIGNEE"), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled
(Title of Invention)

LAYOUT METHOD AND METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE

relating to International Patent Application PCT/JP___/_____and/or for which application for Letters Patent of the United States was executed on even date herewith or, if not so executed, was:

(a) executed on ____________________; *(Insert date of execution of application, if not concurrent)*

(b) filed on ____________________,

Serial No. ____/________________;

Assignee's attorney is hereby authorized to insert in (b) the specified data, when known.

and to said application and all Letters Patent(s) of the United States granted on said application and any continuation, division, renewal, substitute, reissue or reexamination application based thereon, for the full term or terms for which the said Letters Patent(s) may be granted and including any extensions thereof (collectively, hereinafter, "said application(s) and Letters Patent(s)").

The ASSIGNOR agree(s), when requested by said ASSIGNEE and without charge to but at the expense of said ASSIGNEE, to do all acts which the ASSIGNEE may deem necessary, desirable or expedient, for securing, maintaining and enforcing protection for said invention, including in the preparation and prosecution of said application(s) and the issuance of said Letters Patent(s), in any interference, reissue, reexamination, or public use proceeding, and in any litigation or other legal proceeding which may arise or be declared in relation to same, such acts to include but not be limited to executing all papers, including separate assignments and declarations, taking all rightful oaths, providing sworn testimony, and obtaining and producing evidence.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

1)	Takanori Hiramoto *(Signature)*	Takanori HIRAMOTO *(Type Name)*	Apr. 26, 2012 *(Date)*
2)	*(Signature)*	Toshio HINO *(Type Name)*	*(Date)*
3)	*(Signature)*	Tsuyoshi SAKATA *(Type Name)*	*(Date)*
4)	*(Signature)*	Yutaka MIZUNO *(Type Name)*	*(Date)*
5)	*(Signature)*	Katsuya OGATA *(Type Name)*	*(Date)*

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	(Signature)	*(Type Name)*	*(Date)*
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3)		Tsuyoshi SAKATA	
	(Signature)	*(Type Name)*	*(Date)*
4)	Yutaka Mizuno	Yutaka MIZUNO	Apr, 26, 2012
	(Signature)	*(Type Name)*	*(Date)*
5)		Katsuya OGATA	
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